Docket No.: MIY-0214

(PATENT)

## iAP20 Rec'd PCT/PTQ 14 JUN 2006

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Koichi SHIBAYAMA et al.

Application No.: New Application

Confirmation No.: Not Yet Assigned

Filed: Concurrently Herewith

Art Unit: N/A

For: THERMOPLASTIC RESIN COMPOSITION,

MATERIAL FOR SUBSTRATE AND FILM

FOR SUBSTRATE

Examiner: Not Yet Assigned

## **FIRST PRELIMINARY AMENDMENT**

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

## **INTRODUCTORY COMMENTS**

Prior to examination on the merits, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.